BLTJ ET O79.96 786.31 8m56 78m5-999 07-17998-56.-c 76.-c 16 80-39.2-39.2-9.35 ..2-9.35 .9 80-440[(L)3.552-396.5-784055.04-16.587261.532(98.2 c-3.447-795.04.L

Electrical Optical Characteristics at Ta=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
Spectral Sensitivity	λ	400	---	1050	nm	/
Reverse Light Current	I_L	15.5	25	---	μA	V_R=5V Ee=1mW/cm^2 λp=940nm
Reverse Dark Current	I_D	---	---	30	nA	V_R=10V Ee=0mW/cm^2
Reverse Voltage	$V_{(R)}$	30	---	---	V	I_R=100μA
Forward Voltage	V_F	---	---	1.5	V	I_F=20mA
Viewing Angle(X)	$2\theta_{1/2}$	---	120	---	Deg.	(Note 1)
Viewing Angle(Y)	$2\theta_{1/2}$	---	120	---	Deg.	
Rise Time/ Fall Time	tr/tf	---	50	---	ns	V_R=10V RL=1kΩ

- T341.0(i)-2.0(m)-1.9(e)4.0(/) BT /F3 8.03 Tf 1 0 0 1 231.12 4863.55 -460(e)-77565se3.7040 1 45F3 12 T(m)-1.9(e)4.0(/)-3 12 Tonl8 648.4v

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend (Fig.5 and Fig.6).

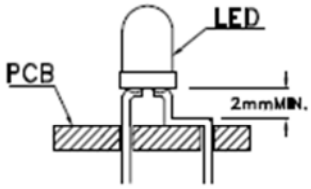

Fig. 5

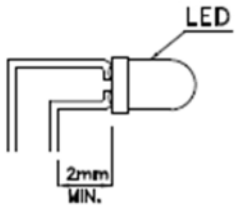

Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after

3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB (Fig.7).
5. Do not bend the leads more than twice (Fig.8).

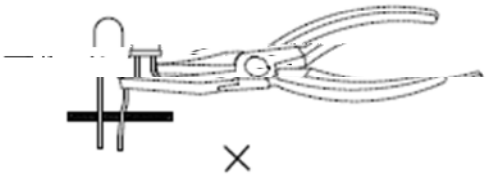

Fig. 7

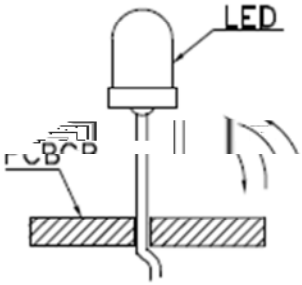

Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig.9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with LIGHT representative for proper handling procedures.

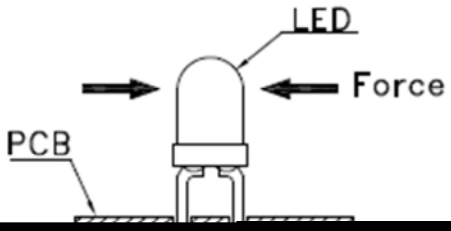

Fig. 9